



Material Content Data Sheet



Sales Product Name		BSC16DN25NS3 G		Issued		2. August 2018		
MA#		MA000847646						
Package		PG-TDSON-8-5		Weight*		124.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.48	1.48	14757	14757
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		91	
	non noble metal	iron	7439-89-6	0.038	0.03		304	
	non noble metal	copper	7440-50-8	37.762	30.37	30.41	303689	304084
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	467	467
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	467	467
encapsulation	organic material	carbon black	1333-86-4	0.095	0.08		764	
	plastics	epoxy resin	-	6.749	5.43		54276	
	inorganic material	silicondioxide	60676-86-0	40.683	32.70	38.21	327179	382219
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11675	11675
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1331	1331
solder	non noble metal	tin	7440-31-5	0.037	0.03		296	
	noble metal	silver	7440-22-4	0.046	0.04		370	
	non noble metal	lead	7439-92-1	1.758	1.41	1.48	14135	14801
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		27	
	non noble metal	iron	7439-89-6	0.011	0.01		91	
	non noble metal	copper	7440-50-8	11.320	9.10	9.11	91039	91157
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		180	
	non noble metal	copper	7440-50-8	22.292	17.93	17.96	179275	179509
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com